TOSHIBA

TOSHIBA Photocoupler GaAlAs Ired & Photo-IC

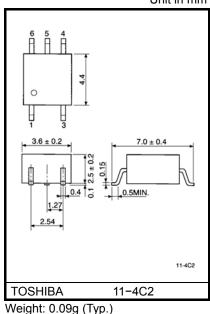
# TLP114A

Digital Logic Isolation Line Receiver Power Supply Control Feedback Control Switching Power Supply Transistor Inverter

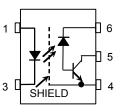
The TOSHIBA mini flat coupler TLP114A is a small outline coupler, suitable for surface mount assembly. TLP114A consists of a high output power GaAlAs light emitting diode, optically coupled to a high speed detector of one chip

photodiode-transistor.

- Isolation voltage: 3750 Vrms (min)
- Switching speed:  $t_{pHL} = 0.8\mu s$ ,  $t_{pLH} = 0.8\mu s$  (max) ( $R_L = 1.9 \text{ k}\Omega$ )
- TTL compatible
- UL recognized: UL1577, file no. E67349



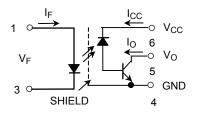
## Pin Configuration (top view)



1 : ANODE 3 : CATHODE

- 4 : EMITTER (GND)
- 5 : COLLECTOR (OUTPUT)
- 6 : V<sub>CC</sub>

#### Schematic



Unit in mm

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
Forward current	(Note 1)	lF	20	mA
Pulse forward current	(Note 2)	I <sub>FP</sub>	40	mA
Peak transient forward current	(Note 3)	I <sub>FPT</sub>	1	А
Reverse voltage		V <sub>R</sub>	5	V
Output current		Ι <sub>Ο</sub>	8	mA
Peak output current		I <sub>OP</sub>	16	mA
Supply voltage		V <sub>CC</sub>	-0.5 to 30	V
Output voltage		VO	-0.5 to 20	V
Output power dissipation	(Note 4)	PO	100	mW
erating temperature range		T <sub>opr</sub>	–55 to 100	°C
rage temperature range		T <sub>stg</sub>	-55 to 125	°C
d solder temperature(10 sec.)		T <sub>sol</sub>	260	°C
Isolation Voltage $(AC 1 \min_{R} R H \le 60^{\circ}\%) $ (Note 5)		BVS	3750	Vrms
	Forward current Pulse forward current Peak transient forward current Reverse voltage Output current Peak output current Supply voltage Output voltage Output voltage Output power dissipation erating temperature range rage temperature range d solder temperature(10 sec.)	Forward current       (Note 1)         Pulse forward current       (Note 2)         Peak transient forward current       (Note 3)         Reverse voltage       0         Output current       Peak output current         Supply voltage       0         Output power dissipation       (Note 4)         erating temperature range       rage temperature range         age temperature range       d solder temperature(10 sec.)         ation Voltage       0	Forward current(Note 1)IFPulse forward current(Note 2)IFPPeak transient forward current(Note 3)IFPTReverse voltageVROutput currentIoPeak output currentIoPeak output currentVCCOutput voltageVCCOutput voltageVOOutput power dissipation(Note 4)PoToprrage temperature rangeTstgd solder temperature(10 sec.)Tsolation VoltageBVS	Forward current(Note 1) $I_F$ 20Pulse forward current(Note 2) $I_{FP}$ 40Peak transient forward current(Note 3) $I_{FPT}$ 1Reverse voltage $V_R$ 5Output current $I_O$ 8Peak output current $I_{OP}$ 16Supply voltage $V_CC$ -0.5 to 30Output voltage $V_O$ -0.5 to 20Output power dissipation(Note 4) $P_O$ 100arating temperature range $T_{opr}$ -55 to 100age temperature range $T_{sol}$ 260ation Voltage $BV_S$ 3750

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- (Note 1) Derate 0.36mA / °C above 70°C.
- (Note 2) 50% duty cycle, Ims pulse width.

Derate 0.72mA / °C above 70°C.

- (Note 3) Pulse width  $\leq$  1µs, 300pps.
- (Note 4) Derate 1.8mW / °C above 70°C.
- (Note 5) Device considered a two-terminal device: Pins 1 and 3 shorted together, and pins 4, 5 and 6 shorted together.

**Electrical Characteristics (Ta = 25°C)** 

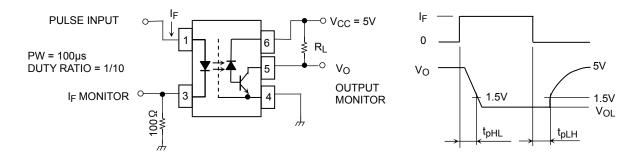
	Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit	
LED	Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 16mA	1.22	1.42	1.72	V	
	Forward voltage temperature coefficient	ΔV <sub>F</sub> / ΔTa	I <sub>F</sub> = 16mA		-2		mV /°C	
	Reverse current	I <sub>R</sub>	V <sub>R</sub> = 3V	—	—	10	μA	
	Capacitance between terminals	CT	V <sub>F</sub> = 0, f = 1MHz	_	30	_	pF	
Detector	High level output current	I <sub>OH (1)</sub>	I <sub>F</sub> = 0mA, V <sub>CC</sub> = V <sub>O</sub> = 5.5V	_	3	500	nA	
		I <sub>OH (2)</sub>	$I_{F} = 0mA, V_{CC} = 30V$ $V_{O} = 20V$	_	_	5		
		ЮН	$I_F = 0mA, V_{CC} = 30V$ $V_O = 20V, Ta = 70^{\circ}C$	_	_	50	μA	
	High level supply current	Іссн	I <sub>F</sub> = 0mA, V <sub>CC</sub> = 30V	_	0.01	1	μA	
Coupled	Current transfer ratio	I <sub>O</sub> / I <sub>F</sub>	$I_F = 16mA$ , $V_{CC} = 4.5V$ $V_O = 0.4V$	20	_	_	%	
	Low level output voltage	V <sub>OL</sub>	$I_{F} = 16mA$ , $V_{CC} = 4.5V$ $I_{O} = 2.4 mA$	_	_	0.4	V	
	Isolation resistance	R <sub>S</sub>	R.H.≤ 60%, V <sub>S</sub> = 500V (Note 5)	5×10 <sup>10</sup>	10 <sup>14</sup>	_	Ω	
	Stray capacitance between input to output	CS	V <sub>S</sub> = 0, f = 1MHz (Note 5)	_	0.8	_	pF	

#### Switching Characteristics (Ta = 25°C, VCC = 5V)

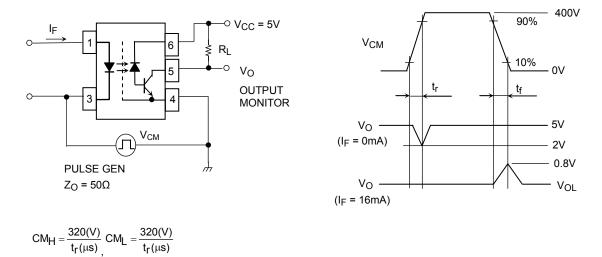
Characteristic	Symbol	Test Cir– cuit	Test Condition	Min.	Тур.	Max.	Unit
Propagation delay time $(H \rightarrow L)$	t <sub>pHL</sub>	1	$I_F = 0 → 16mA$ V <sub>CC</sub> = 5V, R <sub>L</sub> = 1.9kΩ	_	_	0.8	μs
Propagation delay time $(L \rightarrow H)$	t <sub>pLH</sub>	1	IF = 16→ 0mA V <sub>CC</sub> = 5V, R <sub>L</sub> = 1.9kΩ	_	_	0.8	μs
Common mode transient immunity at high output level	C <sub>MH</sub>	2	I <sub>F</sub> = 0mA, V <sub>CM</sub> = 400V <sub>p-p</sub> R <sub>L</sub> = 4.1kΩ	5000	10000	_	V / µs
Common mode transient immunity at low output level	C <sub>ML</sub>	2	$I_F$ = 16mA, V <sub>CM</sub> = 400V <sub>p-p</sub> R <sub>L</sub> = 4.1kΩ	-5000	-10000	_	V / µs

(Note 6) Maximum electrostatic discharge voltage for any pins: 100V (C=200pF, R=0)

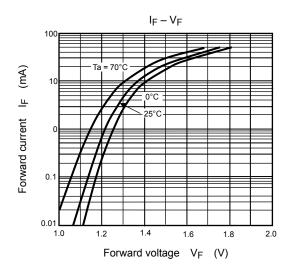
#### Test Circuit 1: Switching Time Test Circuit

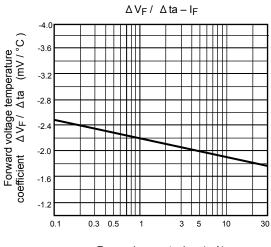


#### Test Circuit =2: Common Mode Transient Immunity Test Circuit

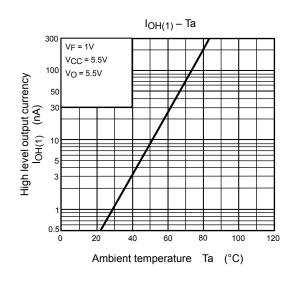


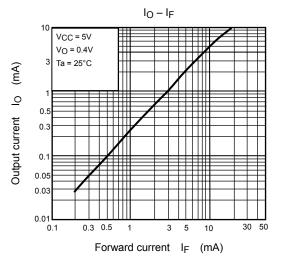
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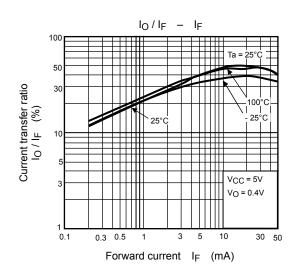




Forward current IF (mA)

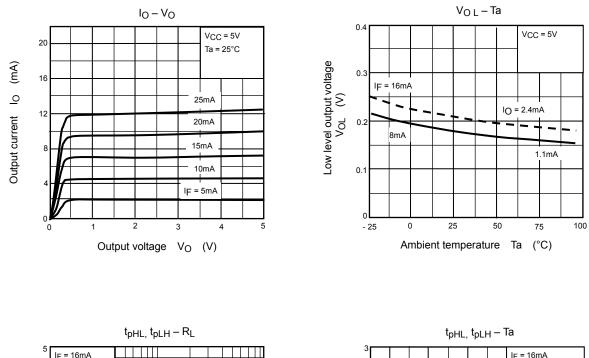


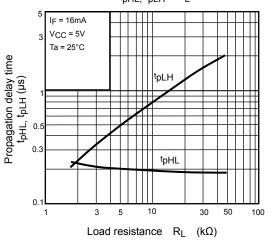


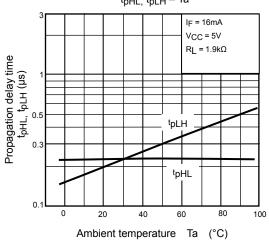


I<sub>O</sub> / I<sub>F</sub> – Ta 1.2 IF = 16mA Nor,alized Io / IF (Io / IF) 1.0 8mA 0.8 Normalized to V<sub>CC</sub> = 4.5V VO = 0.4V 0.6 Ta = 25°C 0.4 0 -20 80 100 0 20 40 60 Ambient temperature Ta (°C)

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